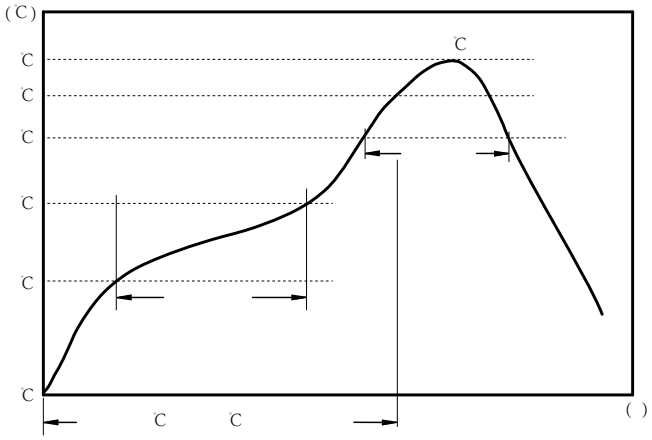
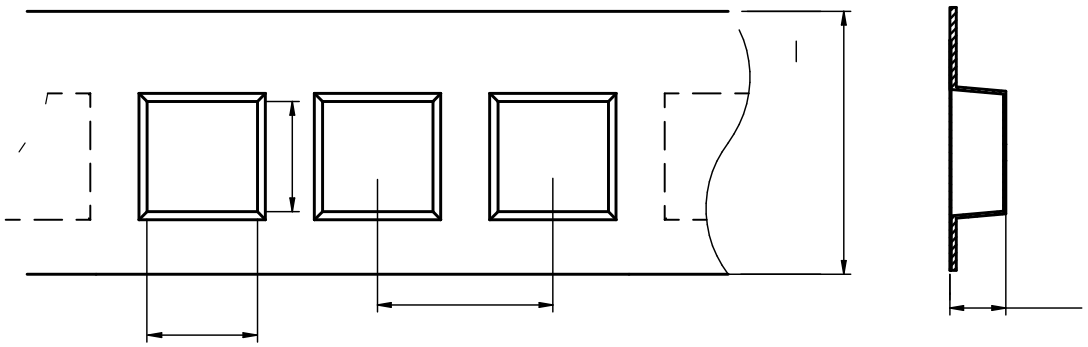


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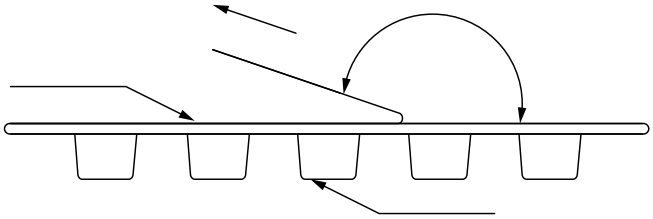
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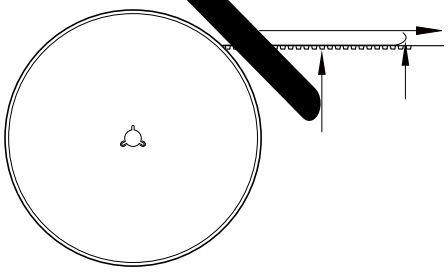
SCM5040	5.3 ± 0.1	5.3 ± 0.1	1.5 ± 0.1	4.0 ± 0.2	12.0 ± 0.1	16.0 ± 0.3	4.6 ± 0.1	1.75 ± 0.1	0.40 ± 0.05

Marking	



The peel force of top cover tape shall be between 0.1 to 1.17 N

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- tions (temperature: -5 to 35ÁC, humidity: 75% RH Max).If the storage period elapses, the soldering of the
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and
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- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient
- Before soldering, be sure to preheat components.The preheating temperature should be set so that the
- tions.If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- Generally, Koher might not be familiar with either customer's specific application or actual requests as customer

  performance described in the product specification is suitable for using in customer's particular application or

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- An open circuit may occur due to mechanical stress from the resin, its amount, cured shape, or operating
-
- Prior to using the coating resin, please verify that no reliability issues are observed.
- When applying conformal coating for product protection, materials with a high shrinkage rate should be avoid ed.If such materials must be used, it is recommended to apply silicone around the inductor core in a closed loop to prevent the conformal coating from flowing into or penetrating the windings, thereby avoiding open-cir cuit failures caused by the coating's thermal stress.